



ULTRA-LOW VOLTAGE PROCESSOR SUPERVISORY CIRCUITS

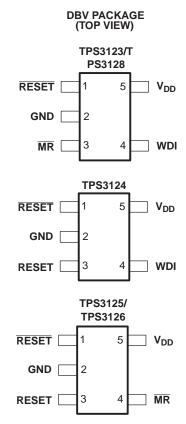
Check for Samples: TPS3123-xx, TPS3124-xx, TPS3125-xx, TPS3126-xx, TPS3128-xx

FEATURES

- Minimum Supply Voltage of 0.75 V
- Supply Voltage Supervision Range:
 - 1.2 V, 1.5 V, 1.8 V (TPS312x)
 - 3 V (TPS3125 Devices Only)
 - Other Versions on Request
- Power-On Reset Generator With Fixed Delay Time of 180 ms
- Manual Reset Input (TPS3123/5/6/8)
- Watchdog Timer Retriggers the RESET Output at V_{DD} ≥ V_{IT}
- Supply Current of 14 µA (Typ)
- Small SOT23-5 Package
- Temperature Range of –40°C to +85°C
- Reset Output Available in Push-Pull (Active Low and High) and Open-Drain (Active-Low)

APPLICATIONS

- Applications Using Low Voltage DSPs, Microcontrollers, or Microprocessors
- · Portable/Battery-Powered Equipment
- Wireless Communication Systems
- Programmable Controls
- Industrial Equipment
- Notebook/Desktop Computers
- · Intelligent Instruments



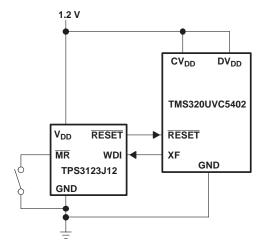


Figure 1. Typical Low-Voltage DSP Application

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

All trademarks are the property of their respective owners.

SLVS227E - AUGUST 1999-REVISED AUGUST 2011

INSTRUMENTS

www.ti.com

DESCRIPTION

The TPS312x family of ultralow voltage processor supervisory circuits provides circuit initialization and timing supervision, primarily for DSP and processor-based systems.

During power-on, $\overline{\text{RESET}}$ is asserted when the supply voltage (V_{DD}) becomes higher than 0.75 V. Thereafter, the supply voltage supervisor monitors V_{DD} and keeps RESET output active as long as V_{DD} remains below the threshold voltage (V_{IT}). An internal timer delays the return of the output to the inactive state (high) to ensure proper system reset. The delay time, $t_d = 180$ ms, starts after V_{DD} has risen above the threshold voltage (V_{IT}).

When the supply voltage drops below the threshold voltage (V_{IT}) , the output becomes active (low) again. No external components are required. All the devices of this family have a fixed-sense threshold voltage (V_{IT}) set by a high precision internal voltage divider.

The TPS3123/5/6/8 devices incorporate a manual reset input, $\overline{\text{MR}}$. A low level at $\overline{\text{MR}}$ causes $\overline{\text{RESET}}$ to become active. The TPS3124 devices do not have the input $\overline{\text{MR}}$, but include a high-level output RESET same as the TPS3125 and TPS3126 devices. In addition, the TPS3123/4/8 have a watchdog timer that needs to be triggered periodically by a positive or negative transition at WDI. When the supervising system fails to retrigger the watchdog circuit within the time-out interval t_{tout} = 0.8 s, $\overline{\text{RESET}}$ output becomes active for the time period (t_d). This event also reinitializes the watchdog timer.

The circuits are available in a 5-pin SOT23-5 package. The TPS312x devices are characterized for operation over a temperature range of -40°C to +85°C.

Table 1. PACKAGE INFORMATION, STANDARD VERSIONS (1)(2)

T _A	DEVIC	E NAME	THRESHOLD VOLTAGE	MARKING
	TPS3123J12DBVR ⁽³⁾	TPS3123J12DBVT ⁽⁴⁾	1.08 V	PBNI
	TPS3123G15DBVR ⁽³⁾	TPS3123G15DBVT ⁽⁴⁾	1.40 V	PBOI
	TPS3123J18DBVR (3)	TPS3123J18DBVT ⁽⁴⁾	1.62 V	PBPI
	TPS3124J12DBVR (3)	TPS3124J12DBVT ⁽⁴⁾	1.08 V	PBQI
	TPS3124G15DBVR ⁽³⁾	TPS3124G15DBVT ⁽⁴⁾	1.40 V	PBRI
	TPS3124J18DBVR (3)	TPS3124J18DBVT ⁽⁴⁾	1.62 V	PBSI
	TPS3125J12DBVR (3)	TPS3125J12DBVT ⁽⁴⁾	1.08 V	PBTI
-40°C to +85°C	TPS3125G15DBVR ⁽³⁾	TPS3125G15DBVT ⁽⁴⁾	1.40 V	PBUI
	TPS3125J18DBVR (3)	TPS3125J18DBVT ⁽⁴⁾	1.62 V	PBVI
	TPS3125L30DBVR (3)	TPS3125L30DBVT ⁽⁴⁾	2.64 V	PBXI
	TPS3126E12DBVR ⁽³⁾	TPS3126E12DBVT ⁽⁴⁾	1.14 V	PFOI
	TPS3126E15DBVR (3)	TPS3126E15DBVT ⁽⁴⁾	1.43 V	PFPI
	TPS3126E18DBVR (3)	TPS3126E18DBVT ⁽⁴⁾	1.71 V	PFQI
	TPS3128E15DBVR (3)	TPS3128E15DBVT ⁽⁴⁾	1.43 V	PFSI
	TPS3128E18DBVR (3)	TPS3128E18DBVT ⁽⁴⁾	1.71 V	PFTI

⁽¹⁾ Other versions available. Contact Texas Instruments for details; minimum order quantities apply.

⁽²⁾ For the most current package and ordering information see the Package Option Addendum at the end of this document, or visit the device product folder at www.ti.com.

⁽³⁾ The DBVR passive indicates tape and reel of 3000 parts.

⁽⁴⁾ The DBVT passive indicates tape and reel of 250 parts.



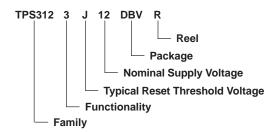


Table 2. Ordering Information Application Specific Versions (1)

DEVICE NAME	NOMINAL SUPPLY VOLTAGE, V _{NOM}	DEVICE NAME	TYPICAL RESET THRESHOLD VOLTAGE-V _{IT-}
TPS312xx12DBV	1.2 V	TPS312xAxxDBV	V _{NOM} -1%
TPS312xx15DBV	1.5 V	TPS312xBxxDBV	V _{NOM} –2%
TPS312xx18DBV	1.8 V	TPS312xCxxDBV	V _{NOM} –3%
TPS312xx30DBV	3.0 V	TPS312xDxxDBV	V _{NOM} –4%
		TPS312xExxDBV	V _{NOM} –5%
		TPS312xFxxDBV	V _{NOM} –6%
		TPS312xGxxDBV	V _{NOM} -7%
		TPS312xHxxDBV	V _{NOM} -8%
		TPS312xlxxDBV	V _{NOM} –9%
		TPS312xJxxDBV	V _{NOM} –10%
		TPS312xKxxDBV	V _{NOM} –11%
		TPS312xLxxDBV	V _{NOM} –12%
			V _{NOM} –13%
		TPS312xNxxDBV	V _{NOM} –14%
		TPS312xOxxDBV	V _{NOM} –15%

⁽¹⁾ For the application-specific versions contact Texas Instruments for availability, lead time, and minimum order quantities.

Table 3. Function Tables

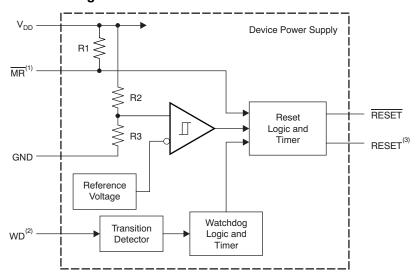
	TPS3123/8			TPS3124		TPS3125/6			
MR	VDD > V _{IT}	RESET	VDD > V _{IT}	RESET	RESET	MR	VDD > V _{IT}	RESET	RESET
L	0	L	0	L	Н	L	0	L	Н
L	1	L	1	Н	L	L	1	L	Н
Н	0	L				Н	0	L	Н
Н	1	Н				Н	1	Н	L

Table 4. Reset Topology

DEVICES	OPEN DRAIN	PUSH-PULL
TPS3123		X
TPS3124		X
TPS3125		X
TPS3126	X	
TPS3128	X	

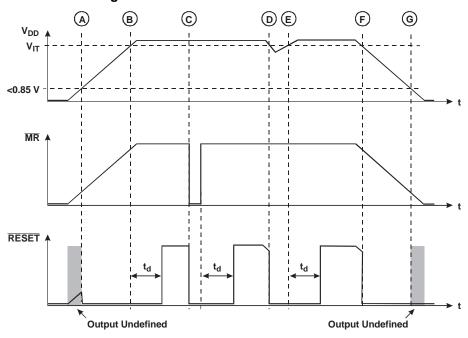


Figure 2. FUNCTIONAL BLOCK DIAGRAM



- NOTES: (1) TPS3123/5/6/8 (2) TPS3123/4/8 (3) TPS3124/5/6

Figure 3. TIMING DIAGRAM TPS3123/5/6/8





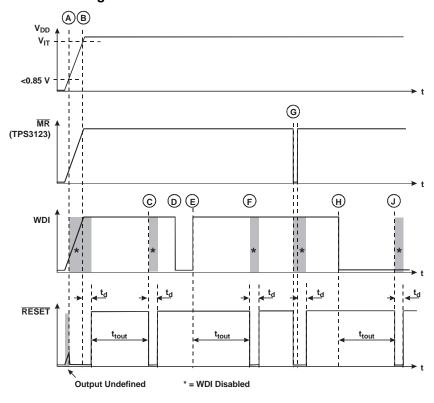


Figure 4. TIMING DIAGRAM TPS3123/4//8

ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range (unless otherwise noted)(1)

		UNIT
	Manual reset, MR	-0.3 V to V _{DD} + 0.6 V
	RESET	$-0.3 \text{ V to V}_{DD} + 0.6 \text{ V}$
V_{DD}	Supply voltage	3.6 V
WDI	Watchdog input	-0.3 V to V _{DD} + 0.6 V
I _{OL}	Maximum low output current	5 mA
I _{OH}	Maximum high output current	–5 mA
I _{IK}	Input clamp current ($V_I < 0$ or $V_I > V_{DD}$)	±10 mA
lok	Output clamp current ($V_O < 0$ or $V_O > V_{DD}$)	±10 mA
	Continuous total power dissipation	See Dissipation Rating Table
T _A	Operating free-air temperature range,	-40°C to +85°C
T _{stg}	Storage temperature range,	−65°C to +150°C
	Soldering temperature	+260°C
	Open drain RESET outputs	-0.3 V to V _{DD} + 0.3 V

⁽¹⁾ Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

DISSIPATION RATING TABLE

PACKAGE	T _A ≤ +25°C	DERATING FACTOR	T _A = +70°C	T _A = +85°C
	POWER RATING	ABOVE T _A = +25°C	POWER RATING	POWER RATING
DBV	437 mW	3.5 mW/°C	280 mW	227 mW



RECOMMENDED OPERATING CONDITIONS

at specified temperature range.

			MIN	MAX	UNIT
V	Cupply voltage	$T_A = 0$ °C to +85°C	0.75	3.3	V
V _{DD}	Supply voltage	$T_A = -40^{\circ}C$ to $+85^{\circ}C$	0.85	3.3	V
V_{DD}	Manual reset voltage		0.0	V _{DD} +0.3	V
V_{WD1}	Watchdog input voltag	е	0	V _{DD} +0.3	V
V_{IH}	High-level input voltag	e	$0.7 \times V_{DD}$		V
V_{IL}	Low-level input voltage			$0.3 \times V_{DD}$	V
Δ t/ΔV	Input transition rise an	d fall rate at WDI		1	μs/V
T _A	Operating free-air tem	perature range	40	+85	°C

ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted).

	PARAMETER		TEST CO	NDITIONS	MIN	TYP	MAX	UNIT	
	MR pullup resistor (internal)					27		kΩ	
	Liber level beaut compart	WDI	$WDI = V_{DD} = 3.3 V$		1		1		
I _{IH}	High-level input current	MR	$\overline{\text{MR}} = 0.7 \times V_{\text{DD}},$	$V_{DD} = 3.3 \text{ V}$	20		55	μΑ	
	Low lovel input ourrent	WDI	WDI = 0 V,	$V_{DD} = 3.3 \text{ V}$	1		1		
I _{IL}	Low-level input current	MR	$\overline{MR} = 0 \text{ V},$	$V_{DD} = 3.3 \text{ V}$	80		170	μA	
I _{OH}	High-level output current (leakage into RESET pin)	TPS3126-xx, TPS3128-xx	$V_{DD} = V_{OH} = 3.3 \text{ V}$				200	nA	
		RESET	$V_{DD} = 1.5 V,$	$I_{OH} = -1 \text{ mA}$					
\/	High-level output voltage	RESET	$V_{DD} = 3.3 V,$	$I_{OH} = -4.5 \text{ mA}$	0.0%\/			V	
V _{OH}	(TPS3123/4/5 only)	RESET	$V_{DD} = 0.75 V,$	$I_{OH} = -8 \mu A$	0.8×V _{DD}			V	
		RESET	$V_{DD} = 1.5 V,$	$I_{OH} = -1 \text{ mA}$					
		RESET	$V_{DD} = 0.75 V,$	$I_{OL} = 15 \mu A$					
V_{OL}	Low-level output voltage	RESET	$V_{DD} = 1.5 V,$	$I_{OL} = 1.4 \text{ mA}$			$0.2 \times V_{DD}$	V	
VOL	Low-level output voltage	RESET	$V_{DD} = 1.5 V,$	$I_{OL} = 1.4 \text{ mA}$				V	
		KESET	$V_{DD} = 3.3 V,$	$I_{OL} = 3 \text{ mA}$			0.4		
		TPS312xJ12			1.04	1.08	1.12		
		TPS312xG15		1.3		1.40	1.45		
		TPS312xJ18			1.56	1.62	1.68	İ	
$V_{\text{IT-}}$	Negative-going input threshold voltage ⁽¹⁾	TPS312xL30	$T_A = -40^{\circ}C \text{ to } +85^{\circ}$	С	2.57	2.64	2.71	V	
	Tolkago	TPS312xE12			1.10	1.14	1.18		
		TPS312xE15			1.38	1.43	1.48		
		TPS312xE18			1.65	1.71	1.77		
			1 V < V _{IT} < 1.4 V			15			
V_{hys}	Hysteresis at V _{DD} input		1.4 V < V _{IT} < 2 V			20		mV	
			2 V < V _{IT} - < 3 V			30			
		TPS3123-xx	$WDI = V_{DD}$	$V_{DD} = 0.75 V$		14			
I _{DD}	Supply current	TPS3124-xx TPS3128-xx	MR unconnected	V _{DD} = 3.3 V		22	30	μA	
00		TPS3125-xx	MR unconnected	$V_{DD} = 0.75 \text{ V}$		14		•	
		TPS3126-xx ⁽²⁾	WIT GIRCOIIIIECIEG	$V_{DD} = 3.3 \text{ V}$	1		25		
C_{i}	Input capacitance at MR, WDI		$V_{I} = 0 V \text{ to } 3.3 V$			5		pF	

⁽¹⁾ To ensure best stability of the threshold voltage, a bypass capacitor (ceramic, 0.1 μ F) should be placed near the supply terminal. (2) The supply current during delay time t_d is typical 5 μ A higher.



TIMING REQUIREMENTS

at $R_L = 1$ M Ω , $C_L = 50$ pF, $T_A = +25$ °C.

	PAR	AMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
		At V _{DD}	$V_{IH} = V_{IT-} + 0.2 \text{ V}, \qquad V_{IL} = V_{IT}0.2 \text{ V}$	6			
t _w	Pulse width	At MR	V 5V +02V V 02×V V 07×V	1			μs
		At WDI	$V_{DD} \ge V_{IT-} + 0.2 \text{ V}, \qquad V_{IL} = 0.3 \text{ x } V_{DD}, \qquad V_{IH} = 0.7 \times V_{DD}$	0.1			

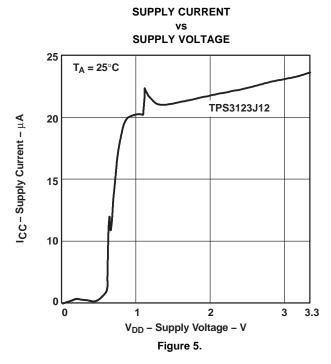
SWITCHING CHARACTERISTICS

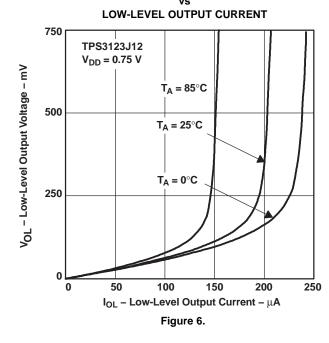
at $R_1 = 1 M\Omega$, $C_1 = 50 pF$, $T_A = +25^{\circ}C$.

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
t _{tout}	Watchdog time out	V _{DD} ≥ V _{IT} + 0.2 V, See timing diagram	0.8	1.4	2.1	s	
t _d	Delay time		V _{DD} > V _{IT} + 0.2 V, See timing diagram	100	180	260	ms
t _{PHL}	Propagation delay time, high-to-low-level output	MR to RESET delay (TPS3123/5/6/8)	V _{DD} ≥ V _{IT} + 0.2 V,			0.1	
t _{PLH}	Propagation delay time, low-to-high-level output	MR to RESET delay (TPS3125/6)	$V_{IL} = 0.2 \times V_{DD},$ $V_{IH} = 0.8 \times V_{DD}$			0.1	μs
t _{PHL}	Propagation delay time, high-to-low-level output	V _{DD} to RESET delay	V V 02V			10	
t _{PLH}	Propagation delay time, low-to-high-level output	V _{DD} to RESET delay (TPS3124/5/6)	$V_{IL} = V_{IT-} - 0.2 \text{ V},$ $V_{IH} = V_{IT-} + 0.2 \text{ V}$			10	μs



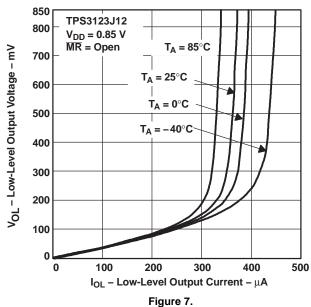
TYPICAL CHARACTERISTICS

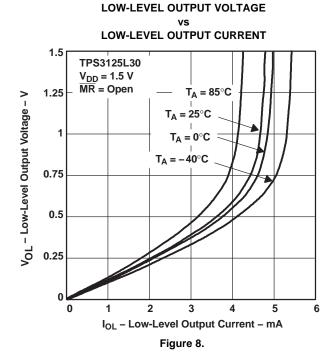




LOW-LEVEL OUTPUT VOLTAGE









TYPICAL CHARACTERISTICS (continued)

LOW-LEVEL OUTPUT VOLTAGE

LOW-LEVEL OUTPUT CURRENT

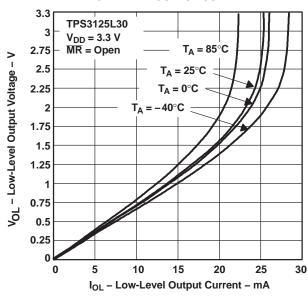


Figure 9.

HIGH-LEVEL OUTPUT VOLTAGE

HIGH-LEVEL OUTPUT CURRENT

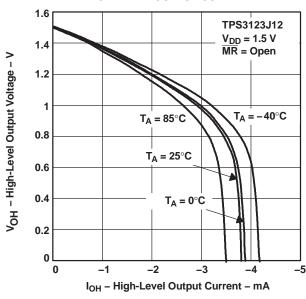


Figure 10.

HIGH-LEVEL OUTPUT VOLTAGE

HIGH-LEVEL OUTPUT CURRENT

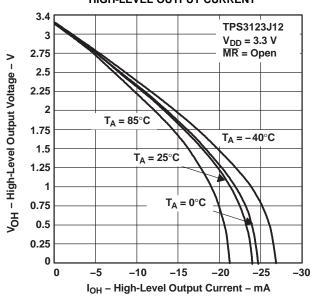


Figure 11.

NORMALIZED INPUT THRESHOLD VOLTAGE

FREE-AIR TEMPERATURE

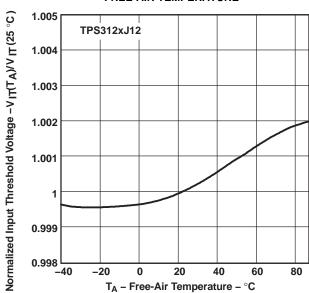


Figure 12.



TYPICAL CHARACTERISTICS (continued)

FREE-AIR TEMPERATURE Normalized Input Threshold Voltage – $\,V_{\,IT}(T_{\,A})^{\prime}\,V_{\,IT}(25\,\,^{\circ}C\,)$ 1.005 TPS312xL30 1.004 1.003 1.002 1.001 1 0.999 0.998 , –40 -20 20 80 0 40 60

 T_A – Free-Air Temperature – °C Figure 13.

NORMALIZED INPUT THRESHOLD VOLTAGE

MINIMUM PULSE DURATION

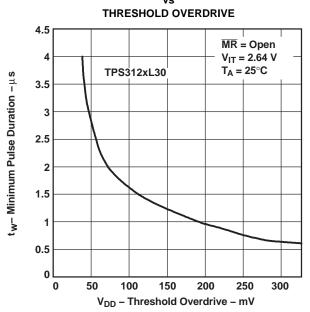
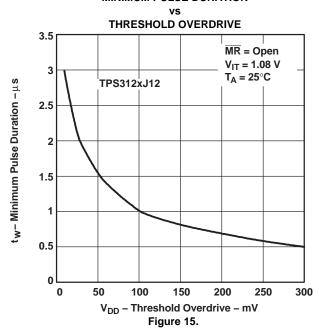


Figure 14.

MINIMUM PULSE DURATION







www.ti.com

REVISION HISTORY

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Cł	nanges from Revision D (December, 2006) to Revision E	Page
•	Removed TPS3128E12DBVR from list of orderable devices in Table 1	2





10-Jun-2014

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
TPS3123G15DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PBOI	Sample
TPS3123J12DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PBNI	Sample
TPS3123J12DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PBNI	Sample
TPS3123J12DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PBNI	Sample
TPS3123J18DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PBPI	Sample
TPS3123J18DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PBPI	Sample
TPS3123J18DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PBPI	Sample
TPS3124G15DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PBRI	Sample
TPS3124J12DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PBQI	Sample
TPS3124J12DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PBQI	Sample
TPS3124J12DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PBQI	Sample
TPS3124J18DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PBSI	Sample
TPS3124J18DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PBSI	Sample
TPS3124J18DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PBSI	Sample
TPS3125G15DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PBUI	Sample
TPS3125G15DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PBUI	Sample
TPS3125G15DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PBUI	Sample



www.ti.com

10-Jun-2014

Orderable Device	rderable Device Status Package Type Package Pins Package Eco Plan Drawing Qty (2)		Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)					
TPS3125G15DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PBUI	Samples
TPS3125J12DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PBTI	Samples
TPS3125J12DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PBTI	Samples
TPS3125J12DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PBTI	Samples
TPS3125J12DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PBTI	Samples
TPS3125J18DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PBVI	Samples
TPS3125J18DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PBVI	Samples
TPS3125J18DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PBVI	Samples
TPS3125J18DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PBVI	Samples
TPS3125L30DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PBXI	Samples
TPS3125L30DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PBXI	Samples
TPS3125L30DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PBXI	Samples
TPS3125L30DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PBXI	Samples
TPS3126E12DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PFOI	Samples
TPS3126E12DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PFOI	Samples
TPS3126E12DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PFOI	Samples
TPS3126E12DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PFOI	Samples
TPS3126E15DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PFPI	Samples





www.ti.com 10-Jun-2014

Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
TPS3126E15DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PFPI	Samples
TPS3126E15DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PFPI	Samples
TPS3126E18DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PFQI	Samples
TPS3126E18DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PFQI	Samples
TPS3126E18DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PFQI	Samples
TPS3128E12DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PFRI	Samples
TPS3128E12DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PFRI	Samples
TPS3128E15DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PFSI	Samples
TPS3128E15DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PFSI	Samples
TPS3128E18DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PFTI	Samples
TPS3128E18DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PFTI	Samples
TPS3128E18DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PFTI	Samples
TPS3128E18DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PFTI	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

TBD: The Pb-Free/Green conversion plan has not been defined.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.



PACKAGE OPTION ADDENDUM

10-Jun-2014

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

PACKAGE MATERIALS INFORMATION

www.ti.com 26-Jan-2013

TAPE AND REEL INFORMATION





	Α0	Dimension designed to accommodate the component width
	B0	Dimension designed to accommodate the component length
	K0	Dimension designed to accommodate the component thickness
	W	Overall width of the carrier tape
г	D1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



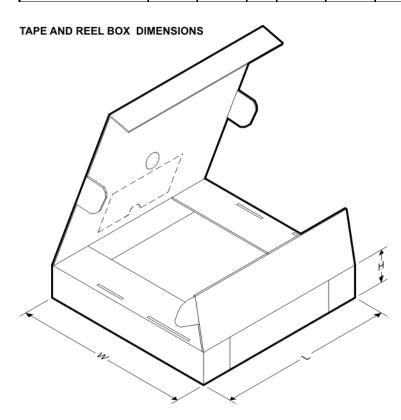
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS3123G15DBVR	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3123J12DBVR	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3123J12DBVT	SOT-23	DBV	5	250	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3123J18DBVR	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3123J18DBVT	SOT-23	DBV	5	250	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3124G15DBVR	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3124J12DBVR	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3124J12DBVT	SOT-23	DBV	5	250	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3124J18DBVR	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3124J18DBVT	SOT-23	DBV	5	250	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3125G15DBVR	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3125G15DBVT	SOT-23	DBV	5	250	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3125J12DBVR	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3125J12DBVT	SOT-23	DBV	5	250	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3125J18DBVR	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3125J18DBVT	SOT-23	DBV	5	250	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3125L30DBVR	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3125L30DBVT	SOT-23	DBV	5	250	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3

PACKAGE MATERIALS INFORMATION

www.ti.com 26-Jan-2013

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS3126E12DBVR	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3126E12DBVT	SOT-23	DBV	5	250	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3126E15DBVR	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3126E15DBVT	SOT-23	DBV	5	250	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3126E18DBVR	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3126E18DBVT	SOT-23	DBV	5	250	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3128E12DBVT	SOT-23	DBV	5	250	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3128E15DBVR	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3128E15DBVT	SOT-23	DBV	5	250	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3128E18DBVR	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3128E18DBVT	SOT-23	DBV	5	250	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS3123G15DBVR	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS3123J12DBVR	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS3123J12DBVT	SOT-23	DBV	5	250	182.0	182.0	20.0
TPS3123J18DBVR	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS3123J18DBVT	SOT-23	DBV	5	250	182.0	182.0	20.0
TPS3124G15DBVR	SOT-23	DBV	5	3000	182.0	182.0	20.0



PACKAGE MATERIALS INFORMATION

www.ti.com 26-Jan-2013

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS3124J12DBVR	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS3124J12DBVT	SOT-23	DBV	5	250	182.0	182.0	20.0
TPS3124J18DBVR	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS3124J18DBVT	SOT-23	DBV	5	250	182.0	182.0	20.0
TPS3125G15DBVR	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS3125G15DBVT	SOT-23	DBV	5	250	182.0	182.0	20.0
TPS3125J12DBVR	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS3125J12DBVT	SOT-23	DBV	5	250	182.0	182.0	20.0
TPS3125J18DBVR	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS3125J18DBVT	SOT-23	DBV	5	250	182.0	182.0	20.0
TPS3125L30DBVR	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS3125L30DBVT	SOT-23	DBV	5	250	182.0	182.0	20.0
TPS3126E12DBVR	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS3126E12DBVT	SOT-23	DBV	5	250	182.0	182.0	20.0
TPS3126E15DBVR	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS3126E15DBVT	SOT-23	DBV	5	250	182.0	182.0	20.0
TPS3126E18DBVR	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS3126E18DBVT	SOT-23	DBV	5	250	182.0	182.0	20.0
TPS3128E12DBVT	SOT-23	DBV	5	250	182.0	182.0	20.0
TPS3128E15DBVR	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS3128E15DBVT	SOT-23	DBV	5	250	182.0	182.0	20.0
TPS3128E18DBVR	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS3128E18DBVT	SOT-23	DBV	5	250	182.0	182.0	20.0

DBV (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
- D. Falls within JEDEC MO-178 Variation AA.



DBV (R-PDSO-G5)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
- D. Publication IPC-7351 is recommended for alternate designs.
- E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.



IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have *not* been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products Applications

Audio www.ti.com/audio Automotive and Transportation www.ti.com/automotive **Amplifiers** amplifier.ti.com Communications and Telecom www.ti.com/communications **Data Converters** dataconverter.ti.com Computers and Peripherals www.ti.com/computers **DLP® Products** www.dlp.com Consumer Electronics www.ti.com/consumer-apps DSP dsp.ti.com **Energy and Lighting** www.ti.com/energy Clocks and Timers www.ti.com/clocks Industrial www.ti.com/industrial Interface interface.ti.com Medical www.ti.com/medical Logic Security www.ti.com/security logic.ti.com

Power Mgmt power.ti.com Space, Avionics and Defense www.ti.com/space-avionics-defense

Microcontrollers microcontroller.ti.com Video and Imaging www.ti.com/video

RFID www.ti-rfid.com

OMAP Applications Processors www.ti.com/omap TI E2E Community e2e.ti.com

Wireless Connectivity www.ti.com/wirelessconnectivity